

Buck Current/Voltage Fed Push-Pull PWM Controllers

FEATURES

- Ideal for Multiple Output and/or High Voltage Output Voltage Converters
- Up to 500kHz Operation
- High Voltage, High Current Floating Driver for Buck Converter Stage
- UC3827-1 Current Fed Controller has Push-Pull Drivers with Overlapping Conduction Periods
- UC3827-2 Voltage Fed Controller has Push-Pull Drivers with Non-overlapping Conduction Periods
- Average Current Mode, Peak Current Mode or Voltage Mode with Input Voltage Feedforward Control for Buck Power Stage
- Wide Bandwidth, Low Offset, Differential Current Sense Amplifier
- Precise Short Circuit Current Control

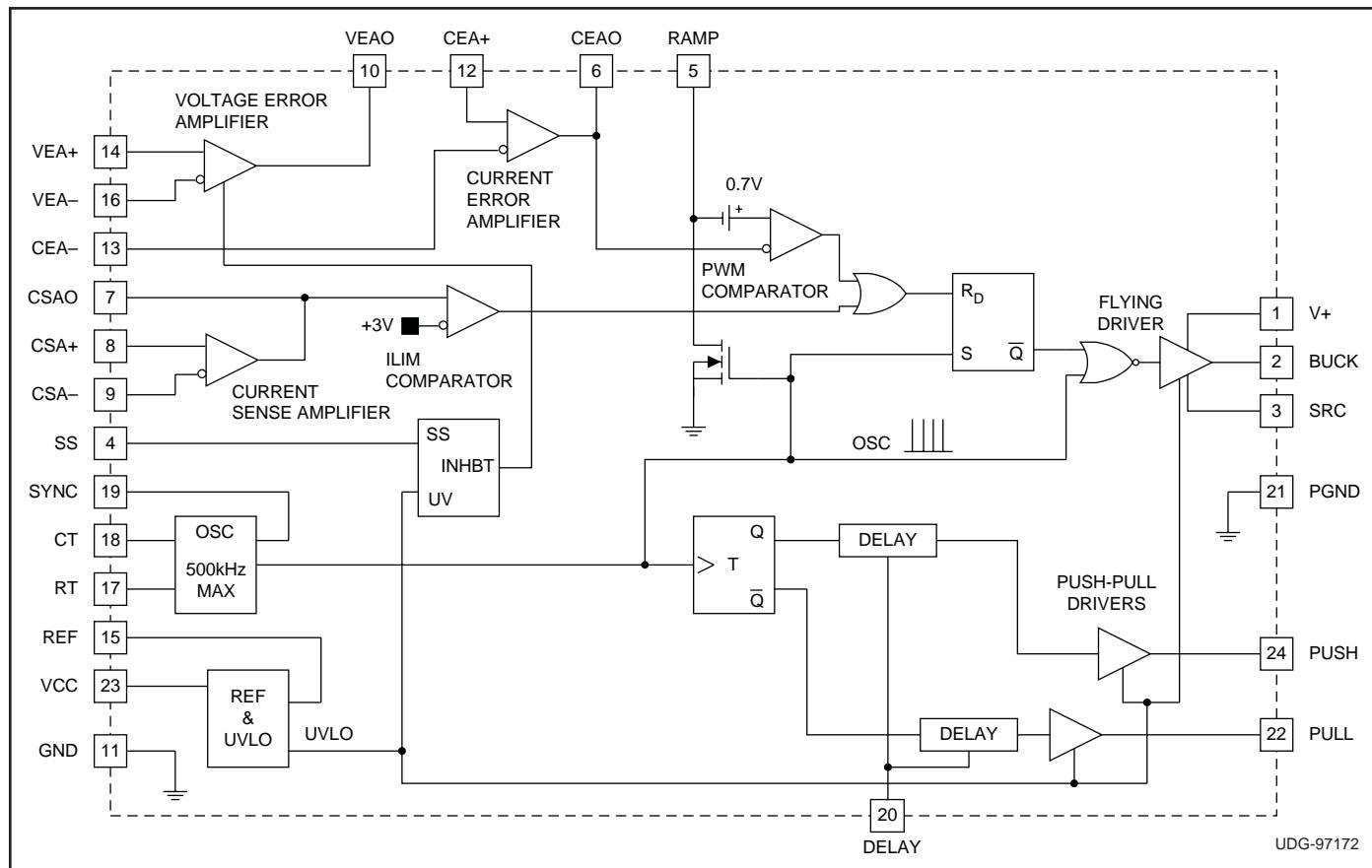
DESCRIPTION

The UC3827 family of controller ICs provides an integrated control solution for cascaded buck and push-pull converters. These converters are known as current fed or voltage fed push-pull converters and are ideally suited for multiple output and/or high voltage output applications. In both current fed and voltage fed modes, the push-pull switches are driven at 50% nominal duty cycles and at one half the switching frequency of the buck stage. In the current fed mode, the two switches are driven with a guaranteed overlap period to prevent ringing and voltage stress on the devices. In the voltage fed mode, the two switches are driven with a guaranteed gap time between the switches to prevent shorting the transformer across the energy storage capacitor and to prohibit excessive currents flowing through the devices.

The converter's output voltage is regulated by pulse width modulation of the buck switch. The UC3827 contains complete protection and PWM control functions for the buck converter. Easy control of the floating switch is accomplished by the floating drive circuitry. The gate drive waveform is level shifted to support an input voltage up to 72Vdc.

(continued)

BLOCK DIAGRAM



DESCRIPTION (cont.)

The UC3827 can be set up in traditional voltage mode control using input voltage feedforward technique or in current mode control. Using current mode control prevents potential core saturation of the push-pull transformer due to mismatches in timing and in component tolerances. With average current mode control, precise control of the inductor current feeding the push-pull stage is possible without the noise sensitivity associated with peak current mode control. The UC3827 average current mode loop can also be connected in parallel with the voltage regulation loop to assist only in fault conditions.

Other valuable features of the UC3827 include bidirectional synchronization capability, user programmable overlap time (UC3827-1), user programmable gap time (UC3827-2), a high bandwidth differential current sense amplifier, and soft start circuitry.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, VCC 20V
Input Voltage Range

For all pins except V+, BUCK, SRC	-0.3V to 5V
For V+ and BUCK	90V
For SRC	90V-VCC
BUCK Driver		
IO Continuous	$\pm 250\text{mA}$
IO Peak	$\pm 1\text{A}$
PUSH/PULL Driver		
IO Continuous	$\pm 200\text{mA}$
IO Peak	$\pm 0.8\text{A}$
Storage Temperature	-65°C to +150°C
Junction Temperature	-55°C to +150°C
Lead Temperature (Soldering, 10 sec.)	+300°C

Voltages are referenced to ground. Currents are positive into, negative out of the specified terminal. Consult Packaging Section of Databook for thermal limitations and considerations of packages.

TEMPERATURE AND PACKAGE SELECTION GUIDE

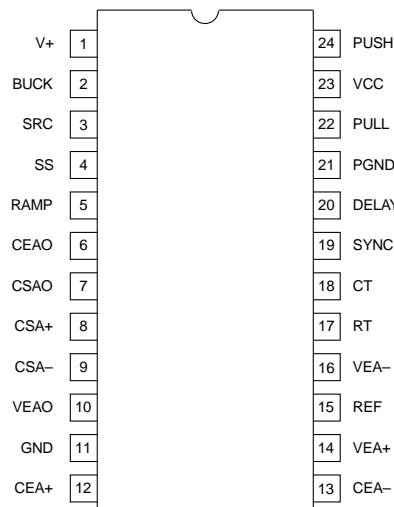
	TEMPERATURE RANGE	AVAILABLE PACKAGES
UC1827-X	-55°C to +125°C	J
UC2827-X	-40°C to +85°C	N, DW, Q
UC3827-X	0°C to +70°C	N, DW, Q

PART VERSION GUIDE

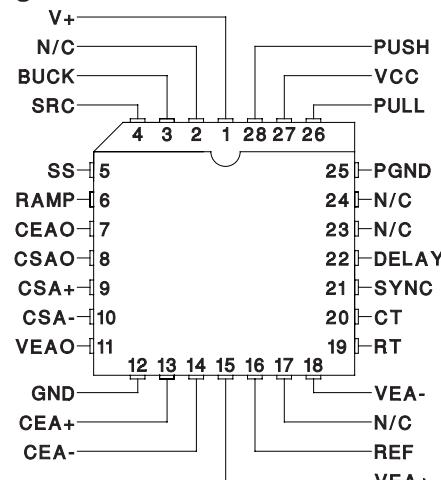
PART NUMBER	TOPOLOGY
UCX827-1	Current Fed Push-Pull
UCX827-2	Voltage Fed Push-Pull

CONNECTION DIAGRAMS

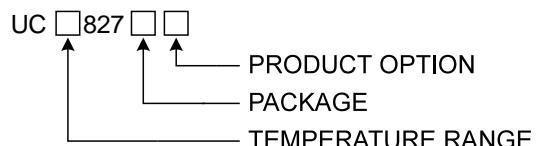
DIL-24 (Top View) N or J, DW Packages



PLCC-28 (Top View) Q Package



ORDERING INFORMATION



ELECTRICAL CHARACTERISTICS Unless otherwise specified, VCC = 15V, V+ = 14.3V, CT = 340pF, RT = 10K, RDELAY = 24.3k, SRC = GND, BUCK, PUSH and PULL outputs no load. TJ = TA.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Supply					
VCC UVLO, Turn-On		8.3	8.8	9.5	V
Hysteresis		0.9	1.2	1.5	V
IVCC Start	VCC = 8V			1000	µA
IVCC Run			32	45	mA
V+ UVLO, Turn-On		7.1	7.5	8.3	V
V+ Hysteresis		0.2	0.4	0.9	V
IV+ Buck High		0.2	1	2	mA
Voltage Error Amplifier					
IB			0.5	3	µA
VIO				10	mV
AVOL		80	95		dB
GBW	(Note 7)	1	4		MHz
VOL	IV _{EA0} = 0µA (No Load)		0.3	0.5	V
VOH	IV _{EA0} = 0µA (No Load)	2.85	3	3.20	V
Current Sense Amplifier					
IB			-1	-5	uA
VIO				5	mV
AVOL		80	110		dB
GBW	(Note 7)	15	29		MHz
VOL	IC _{EA0} = 0µA (No Load)		0.25	0.5	V
VOH	IC _{EA0} = 0µA (No Load)	3	3.3		V
Common Mode Range	(Note 7)	0		2	V
Current Error Amplifier					
IB			-1	-5	µA
VIO				10	mV
AVOL		80	110		dB
GBW	At 100kHz, Measure Gain	2	4.5		MHz
VOL	IC _{EA0} = 0µA (No Load)		0.25	0.5	V
VOH	IC _{EA0} = 0µA (No Load)	3.3	3.5		V
Common Mode Range	(Note 7)	0		5	V
Oscillator Section					
Frequency		180	220	250	kHz
CT Discharge Current	3.5V at CT when CT removed	5			mA
PWM Comparator					
Minimum Duty Cycle	200kHz			0	%
Maximum Duty Cycle	200kHz	85	91	95	%
Buck Output Stage					
Rise Time	1nF Load, (Note 3)		40	100	ns
Fall Time	1nF, Load		30	80	ns
VOH	I _{BUCK} = -15mA , V+ - BUCK (Note 4)	1.5	2.5		V
	I _{BUCK} = -150mA, V+ - BUCK (Note 4)	2	2.5		V
VOL	I _{BUCK} = 15mA (Note 5)		0.2	0.4	V
	I _{BUCK} = 150mA (Note 5)	0.7	1.2		V

ELECTRICAL CHARACTERISTICS Unless otherwise specified, VCC = 15V, V+ = 14.3V, CT = 340pF, RT = 10K, RDELAY = 24.3k, SRC = GND, BUCK, PUSH and PULL outputs no load. TJ = TA.

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Push/Pull Output Stages					
Rise Time	1nF Load		50	100	ns
Fall Time	1nF Load		35	100	ns
Overlap Time, -1 Only	1nF loads (Note 1)	100	250	400	ns
Non-Overlapping Time, -2 Only	(Note 2)	100	250	500	ns
VOH	IPUSH/PULL = -10mA, VCC – PUSH (Note 6)		2	3	V
	IPUSH/PULL = -100mA, VCC – PUSH (Note 6)		2.5	3	V
VOL	IPUSH/PULL = 10mA (Note 6)		0.2	0.8	V
	IPUSH/PULL = 100mA (Note 6)		0.6	1.2	V
Reference					
REF Voltage		4.8	5	5.2	V
Short Circuit Current	REF = 0V	-35	-50	-65	mA
Line Regulation	9.5V < VCC < 20V		5	20	mV
Load Regulation	0mA < IO < 10mA		8	20	mV
Soft Start					
VOL, Saturation	VCC = 7V		250	500	mV
Iss		-5	-12	-25	µA

Note 1: The overlap time is measured from the point at which the rising edge of PUSH/PULL crosses 5V until the falling edge of PUSH/PULL crosses 5V.

Note 2: The non-overlap time is measured from the point at which the falling edge of PUSH/PULL crosses 5V until the rising edge of PUSH/PULL crosses 5V.

Note 3: Measure the rise time from when BUCK crosses 1V until it crosses 9V.

Note 4: To force BUCK high, force CSAO=2.5V, CEA0 = 2.5V, a 25k pulldown resistor from RAMP to ground, and CT = 0.5V.

Note 5: To force BUCK low, force CSAO = 2.5V, CEA0 = 2.5V, a 10k pulldown resistor from RAMP to ground, and CT = 3.5V.

Note 6: To toggle PUSH or PULL into a desired state, pulse CT from 0.5V to 3.5V. PUSH and PULL toggle on the rising edge of CT.

Note 7: Guaranteed by design. Not 100% tested in production.

PIN DESCRIPTIONS

BUCK: Output of the buck PWM controller. The BUCK output is a floating driver, optimized for controlling the gate of an N-channel MOSFET. The peak sink and source currents are 1A. Any undervoltage faults will disable BUCK to an off condition (low).

CEA+: The non-inverting input of the current error amplifier.

CEA-: The inverting input of the current error amplifier.

CEAO: The output of the current error amplifier and the inverting input of the PWM comparator of the buck converter.

CSA+: The noninverting input of the current sense amplifier.

CSA-: The inverting input of the current sense amplifier.

CSAO: The output of the current sense amplifier and the noninverting input of the current limit comparator. When the signal level on this pin exceeds the 3V threshold of the current limit comparator, the buck gate drive pulse is terminated. This feature is useful to implement cycle-by-cycle current limiting for the buck converter.

CT: This pin is provided for the timing capacitor which is connected between CT and GND. The oscillator frequency is set by CT and a resistor RT, connected between pin RT and GND. The CT discharge current is approximately 40X the bias current through the resistor connected to RT. A practical maximum value for the discharge current is 20mA. The frequency of the oscillator is given by:

$$f_{OSC} = \frac{0.77}{RT \cdot CT}$$

PIN DESCRIPTIONS (cont.)

DELAY: A resistor to GND programs the overlap time of the PUSH and PULL outputs of the UC3827-1 and the dead time of the PUSH and PULL outputs of the UC3827-2. The minimum value of the resistor, RDELAY, is 18kΩ. The delay or overlap time is given by:

$$T_{DELAY} = \frac{R_{DELAY}}{200\Omega} \cdot 10^{-9} \text{ sec.}$$

GND: This pin is the ground reference for all sensitive setup components not related to driving the outputs. They include all timing, voltage sense, current sense, and bypass components.

PGND: Ground connection for the PUSH and PULL outputs. PGND must be connected to GND at a single point on the printed circuit board. This is imperative to prevent large, high frequency switching currents flowing through the ground metalization inside the IC.

PULL: Ground referenced output to drive an N-channel MOSFET. The PULL and the PUSH outputs are driving the two switches of the push-pull converter with complementary signals at close to a 50% duty cycle. Any undervoltage faults will disable PULL to an off condition (low).

PUSH: Ground referenced output to drive an N-channel MOSFET. The PULL and the PUSH outputs are driving the two switches of the push-pull converter with complementary signals at close to a 50% duty cycle. Any undervoltage faults will disable PUSH to an off condition (low).

RAMP: The RAMP voltage, after a 700mV internal level shift, is fed to the noninverting input of the buck PWM comparator. A resistor to Vin and a capacitor to GND provide an input voltage feedforward signal for the buck controller in voltage mode control. In peak current mode control, the RAMP pin receives the current signal of the buck converter. In an average current mode setup, the RAMP pin has a linearly increasing ramp signal. This waveform may be generated either by connecting RAMP directly to CT, or by connecting both a resistor from VCC to RAMP and a capacitor from RAMP to GND.

REF: The output of the +5V on board reference. Bypass this pin with a capacitor to GND. The reference is off when the chip is in undervoltage lockout mode.

RT: A resistor to GND programs the charge current of the timing capacitor connected to CT. The charge current approximately equals:

REF
2•RT

The charge current should be less than 500µA to keep CT's discharge peak current less than 20mA, which is CT's maximum practical discharge value. The discharge time, which sets the maximum duty cycle, is set internally and is influenced by the charge current.

SRC: The source connection for the floating buck switch. The voltage on the SRC pin can exceed VCC but must be lower than 90V-VCC. Also, during turn-off transients of the buck switch, the voltage at SRC can go to -2V.

SS: The soft start pin requires a capacitor to GND. During soft start the output of the voltage error amplifier is clamped to the soft start capacitor voltage which is slowly charged by an internal current source. In UVLO, SS is held low.

SYNC: SYNC is a bidirectional pin for the oscillator. This pin can be used to synchronize several chips to the fastest oscillator. Its input synchronization threshold is 1.4V. The SYNC voltage is 3.6V when the oscillator capacitor, CT, is discharged. Otherwise it is 0V. If the recommended synchronization circuit is not used, a 1k or lower value resistor from SYNC to GND may be needed to increase the fall time of the signal at SYNC.

VCC: A voltage source connected to this pin supplies the power for the UC3827. It is recommended to bypass this pin to both GND and PGND ground connections with good quality high frequency capacitors.

VEA+: The non-inverting input of the voltage error amplifier.

VEA-: The inverting input of the voltage error amplifier.

VEAO: The output of the voltage error amplifier.

V+: Supply voltage for the buck output. The floating driver of the UC3827 uses the bootstrap technique which requires a reservoir capacitor to store the required energy for the on time of the buck switch. A diode must be connected from VCC to V+ to charge the reservoir capacitor. This diode must be able to withstand Vin. The reservoir capacitor must be connected between V+ and SRC and its voltage is monitored directly by the undervoltage lockout circuitry of the buck driver.

APPLICATION INFORMATION

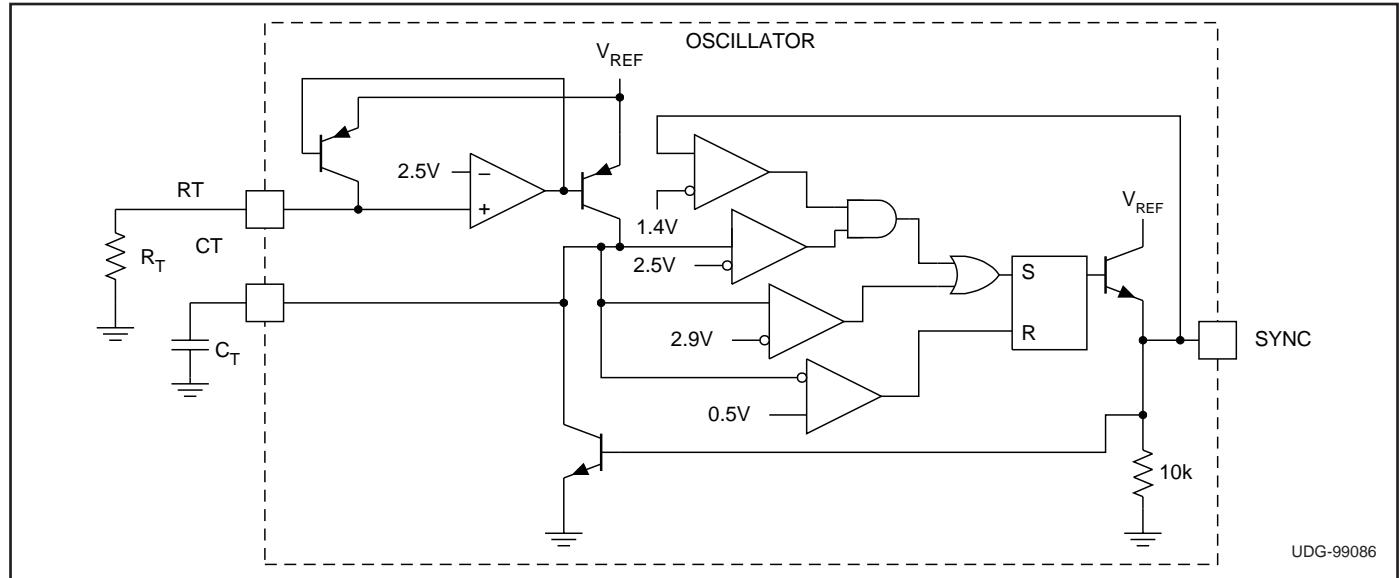


Figure 1. Oscillator block with external connections.

CIRCUIT BLOCK DESCRIPTION

PWM Oscillator. The oscillator block diagram with external connections is shown in Fig. 1. A resistor (R_T) connected to pin RT sets the linear charge current:

$$I_{RT} \approx \frac{2.5V}{R_T}$$

The timing capacitor (C_T) is linearly charged with the charge current forcing the OSC pin to charge to a 3.4V threshold. After exceeding this threshold, the RS flip-flop is set driving CLKSYN high and RDEAD low which discharges C_T . C_T continues to discharge until it reaches a 0.5V threshold and resets the RS flip-flop which repeats the charging sequence as shown in Fig. 2.

As shown in Fig. 3, several oscillators are synchronized to the highest free running frequency by connecting 100pF capacitors in series with each CLKSYN pin and connecting the other side of the capacitors together forming the CLKSYN bus. The CLKSYN bus is then pulled down to ground with a resistance of approximately 10k. Referring to Fig. 1, the synchronization threshold is 1.4V. The oscillator blanks any synchronization pulse that occurs when OSC is below 2.5V. This allows units, once they discharge below 2.5V, to continue through the current discharge and subsequent charge cycles whether or not other units on the CLKSYN bus are still synchronizing. This requires the frequency of all free running oscillators to be within 17% of each other to guarantee synchronization.

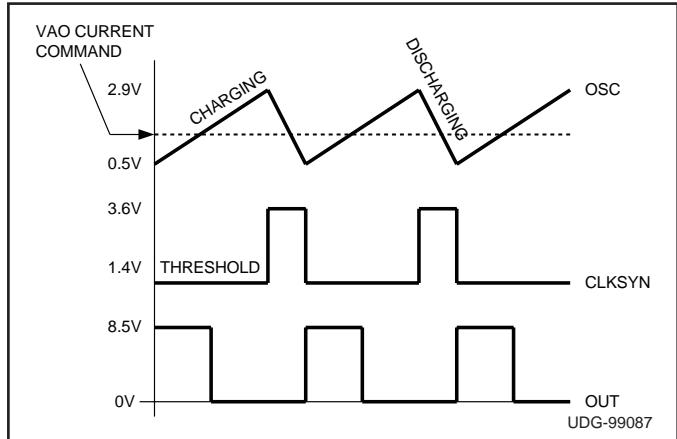


Figure 2. Oscillator and PWM output waveform.

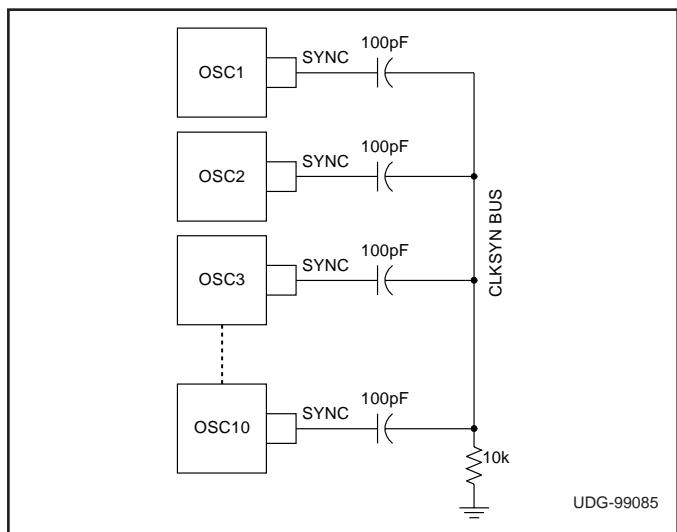


Figure 3. Oscillator synchronization connection diagram.

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